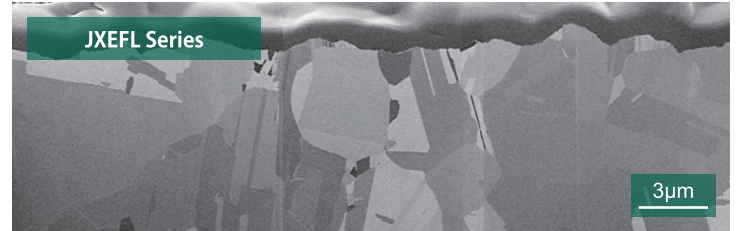
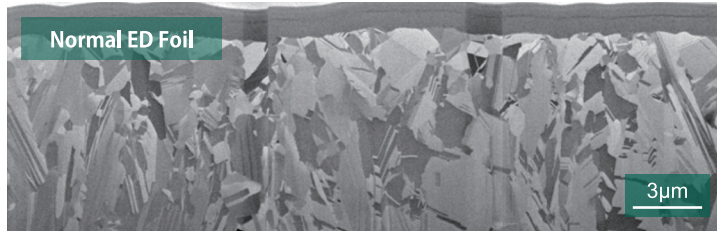


# Electro-deposited Copper Foil for FPC “JXEFL”

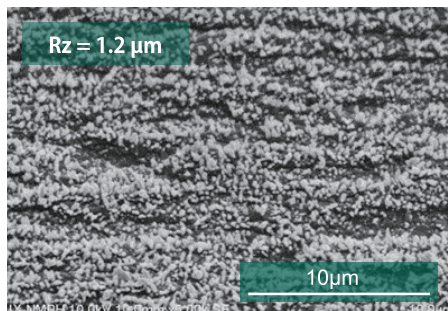
- JXEFL-BHM : low loss & low roughness copper foil for Modified-PI film.
- JXEFL-FX : low loss & high peel strength copper foil for LCP film.
- JXEFL-V2 : standard copper foil for all kinds of FPC.

## Crystal structure

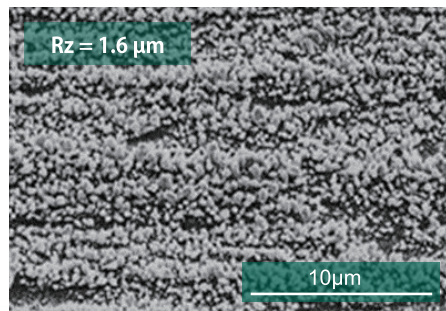


Typical Properties		JXEFL-BHM	JXEFL-FX	JXEFL-V2
Thickness	[µm]	9, 12, 18, 35	12, 18	9, 12, 18, 25, 35, 50, 70
Thickness	[oz/inch <sup>2</sup> ]	1/4, 1/3, 1/2, 1	1/3, 1/2	1/4, 1/3, 1/2, 3/4, 1, 3/2, 2
Tensile (R.T.)	[MPa]	420	420	420
	[kpsi]	62	62	62
Elongation (R.T.)	%	8	8	8
Roughness Ra Shiny Side	[µm]	0.3	0.3	0.3
Roughness Rz Matte Side	[µm]	1.2	1.6	1.7
Peel strength (FR-4)	[kN/m]	0.7	0.8	0.8
	[lbs/in]	4.0	4.6	4.6
Suitable film materials		MPI	LCP	PI

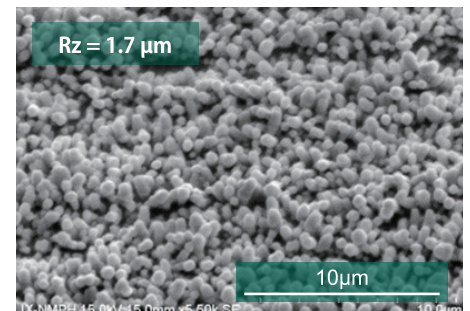
## Bond side profile (x5000)



JXEFL-BHM



JXEFL-FX



JXEFL-V2